

CHIP COIL (CHIP INDUCTORS) LQH43NZ□□□□03L
Murata Standard Reference Specification [AEC-Q200]

1.Scope

This reference specification applies to LQH43NZ series, Chip coil (Chip Inductors) for automotive Electronics based on AEC-Q200 except for Power train and Safety.

2.Part Numbering

(ex)	LQ	H	43	N	Z	1R0	M	0	3	L
	Product ID	Structure	Dimension (L×W)	Applications and Characteristics	Category	Inductance	Tolerance	Features	Electrode	Packaging L:Taping

3.Rating

- Operating Temperature Range. -40 °C to +105 °C
- Storage Temperature Range. -40 °C to +105 °C

Customer's Part Number	MURATA Part Number	Inductance		Q (min.)	DC Resistance (Ω max)	Self Resonant Frequency (MHz min)	*1:Rated Current (mA)	ESD 1C : 1kV
		(μH)	Tolerance (%)					
	LQH43NZ1R0M03L	1.0	M:±20	20	0.20	120	500	1C
	LQH43NZ1R2M03L	1.2				100		
	LQH43NZ1R5M03L	1.5			0.30	85		
	LQH43NZ1R8M03L	1.8				75		
	LQH43NZ2R2M03L	2.2			0.32	62		
	LQH43NZ2R7M03L	2.7				53		
	LQH43NZ3R3M03L	3.3				47		
	LQH43NZ3R9M03L	3.9				41		
	LQH43NZ4R7M03L	4.7	M:±20 K:±10	30		0.40	38	
	LQH43NZ4R7K03L							
	LQH43NZ5R6M03L	5.6			0.47	33		
	LQH43NZ5R6K03L							
	LQH43NZ6R8M03L	6.8			0.50	31	450	
	LQH43NZ6R8K03L							
	LQH43NZ8R2M03L	8.2			0.56	27		
	LQH43NZ8R2K03L							
	LQH43NZ100K03L	10	K:±10 J:± 5	35	0.62	23	400	
	LQH43NZ100J03L							
	LQH43NZ120K03L	12			0.73	19	360	
	LQH43NZ120J03L							
	LQH43NZ150K03L	15			0.82	17	340	
	LQH43NZ150J03L							
	LQH43NZ180K03L	18			0.94	15	320	
	LQH43NZ180J03L							
	LQH43NZ220K03L	22	1.1	14	300			
	LQH43NZ220J03L							
	LQH43NZ270K03L	27	1.2	12	270			
	LQH43NZ270J03L							
	LQH43NZ330K03L	33	1.4	11	240			
	LQH43NZ330J03L							
	LQH43NZ390K03L	39						
	LQH43NZ390J03L							

Customer's Part Number	MURATA Part Number	Inductance		Q (min.)	DC Resistance (Ω max)	Self Resonant Frequency (MHz min)	*1:Rated Current (mA)	ESD 1C : 1kV
		(μ H)	Tolerance (%)					
	LQH43NZ470K03L	47	K:±10 J:± 5	35	1.5	10	220	1C
	LQH43NZ470J03L							
	LQH43NZ560K03L	56			1.7	9.3	200	
	LQH43NZ560J03L							
	LQH43NZ680K03L	68			1.9	8.4	180	
	LQH43NZ680J03L							
	LQH43NZ820K03L	82		2.2	7.5	170		
	LQH43NZ820J03L							
	LQH43NZ101K03L	100		2.5	6.8	160		
	LQH43NZ101J03L							
	LQH43NZ121K03L	120		3.0	6.2	150		
	LQH43NZ121J03L							
	LQH43NZ151K03L	150		3.7	5.5	130		
	LQH43NZ151J03L							
	LQH43NZ181K03L	180		4.5	5.0	120		
	LQH43NZ181J03L							
	LQH43NZ221K03L	220		5.4	4.5	110		
	LQH43NZ221J03L							
	LQH43NZ271K03L	270		6.8	4.0	100		
	LQH43NZ271J03L							
	LQH43NZ331K03L	330		8.2	3.6	95		
	LQH43NZ331J03L							
	LQH43NZ391K03L	390		9.7	3.3	90		
	LQH43NZ391J03L							
	LQH43NZ471K03L	470	11.8	3.0	80			
	LQH43NZ471J03L							
	LQH43NZ561K03L	560	14.5	2.7	70			
	LQH43NZ561J03L							
	LQH43NZ681K03L	680	17.0	2.5	65			
	LQH43NZ681J03L							
	LQH43NZ821K03L	820	20.5	2.2	60			
	LQH43NZ821J03L							
	LQH43NZ102K03L	1000	25.0	2.0	50			
	LQH43NZ102J03L							
	LQH43NZ122K03L	1200	30.0	1.8	45			
	LQH43NZ122J03L							
	LQH43NZ152K03L	1500	37.0	1.6	40			
	LQH43NZ152J03L							
	LQH43NZ182K03L	1800	45.0	1.5	35			
	LQH43NZ182J03L							
	LQH43NZ222K03L	2200	50.0	1.3	30			
	LQH43NZ222J03L							
	LQH43NZ242K03L	2400	53	1.2	25			
	LQH43NZ242J03L							

*1:When applied Rated current to the Products , self temperature rise shall be limited to 20°C max and Inductance will be within ±10% of initial Inductance value.

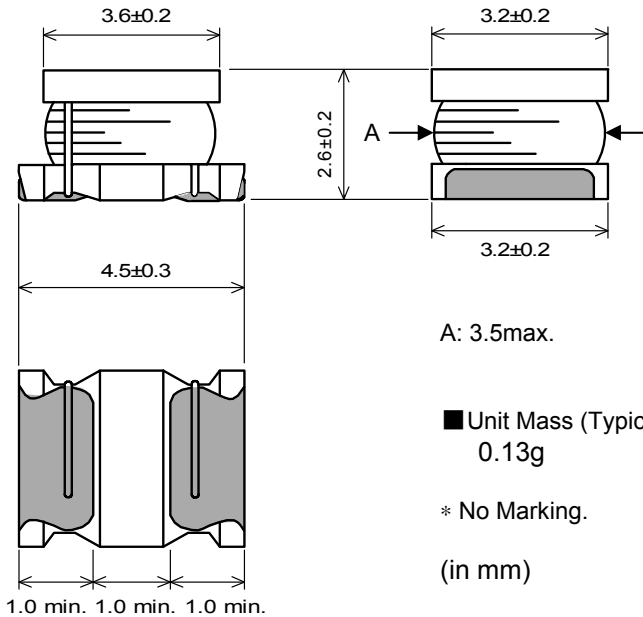
4. Testing Conditions

《Unless otherwise specified》

Temperature : Ordinary Temperature / 15°C to 35°C
 Humidity : Ordinary Humidity / 25%(RH) to 85%(RH)

《In case of doubt》

Temperature : 20 ± 2°C
 Humidity : 60%(RH) to 70%(RH)
 Atmospheric Pressure : 86kPa to 106 kPa

**5. Appearance and Dimensions (No marking)
LQH43N (without coating) Type****6. Electrical Performance**

No.	Item	Specification	Test Method
6.1	Inductance	Inductance shall meet item 3.	Measuring Equipment: KEYSIGHT 4192A or equivalent Measuring Frequency: 1MHz / 1.0 to 390μH 1kHz / 470 to 2400μH
6.2	Q		Measuring Equipment: KEYSIGHT 4192A or equivalent Measuring Frequency: 1MHz / 1.0 to 82μH 796kHz / 100 to 820μH 252kHz / 1000 to 2400 μH
6.3	DC Resistance	DC Resistance shall meet item 3.	Measuring Equipment: Digital multi meter
6.4	Self Resonant Frequency(S.R.F)	S.R.F shall meet item 3.	Measuring Equipment: KEYSIGHT E4991A or equivalent
6.5	Rated Current	Self temperature rise shall be limited to 20°C max. Inductance Change : within ± 10%	The rated current is applied.

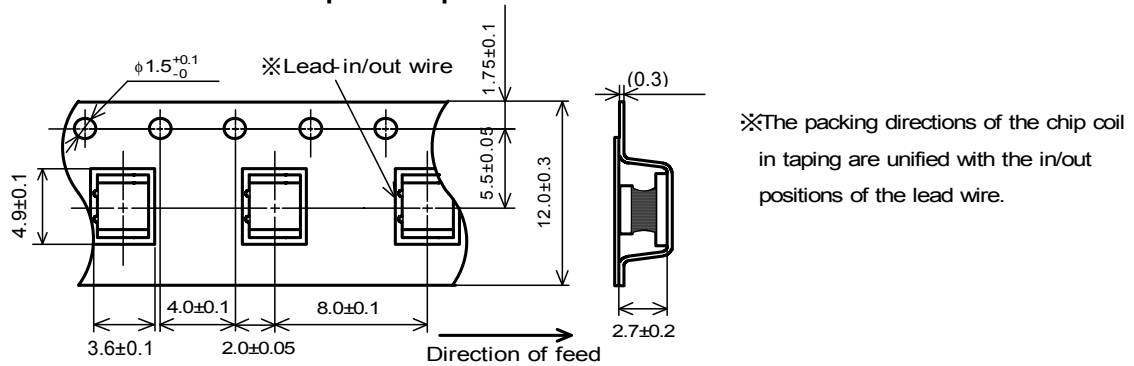
7. AEC-Q200 Requirement**7.1 Performance (based on Table 5 for Magnetics(Inductors / Transformer)****AEC-Q200 Rev.D issued June. 1 2010**

AEC-Q200			Murata Specification / Deviation						
No	Stress	Test Method							
3	High Temperature Exposure	1000hours at 105 deg C Set for 24hours at room temperature, then measured.	Meet Table A after testing. Table A <table border="1"> <tr> <td>Appearance</td> <td>No damage</td> </tr> <tr> <td>Inductance change</td> <td>Within ±5%</td> </tr> <tr> <td>Q change</td> <td>Within ±20%</td> </tr> </table>	Appearance	No damage	Inductance change	Within ±5%	Q change	Within ±20%
Appearance	No damage								
Inductance change	Within ±5%								
Q change	Within ±20%								
4	Temperature Cycling	1000cycles -40 deg C to + 105deg C Set for 24hours at room temperature, then measured.	Meet Table A after testing.						
7	Biased Humidity	1000hours at 85 deg C, 85%RH unpowered..	Meet Table A after testing.						
8	Operational Life	Apply 105 deg C 1000 hours Set for 24hours at room temperature, then measured	Meet Table A after testing.						
9	External Visual	Visual inspection	No abnormalities						
10	Physical Dimension	Meet ITEM 5 (Style and Dimensions)	No defects						
12	Resistance to Solvents	Per MIL-STD-202 Method 215	Not Applicable						
13	Mechanical Shock	Per MIL-STD-202 Method 213 100g's/6ms/Half sine	Meet Table A after testing.						
14	Vibration	5g's for 20 minutes, 12cycles eah of 3 orientations Test from 10-2000Hz. 12cycles each of 3 orientations	Meet Table A after testing.						
15	Resistance to Soldering Heat	No-heating Solder temperature 260C+/-5 deg C Immersion time 10s	Meet Table A after testing.						
17	ESD	Per AEC-Q200-002	Meet Item 3 (Rating) No defects						
18	Solderbility	Per J-STD-002	Method B : Not Applicable 95% of the terminations is to be soldered. (Except exposed wire)						
19	Electrical Characterization	Measured : Inductance	No defects						

AEC-Q200			Murata Specification / Deviation				
No	Stress	Test Method					
20	Flammability	Per UL-94	Not Applicable				
21	Board Flex	Epoxy-PCB(1.6mm) Deflection 2mm(min) 60s minimum holding time	Murata deviation request: 5s Meet Table B after testing. Table B <table border="1" style="margin-left: 20px;"> <tr> <td>Appearance</td> <td>No damage</td> </tr> <tr> <td>DC resistance change</td> <td>Within ±10%</td> </tr> </table>	Appearance	No damage	DC resistance change	Within ±10%
Appearance	No damage						
DC resistance change	Within ±10%						
22	Terminal Strength	Per AEC-Q200-006 A force of 17.7N for 60s	No defects				

8. Specification of Packaging

8.1 Appearance and Dimensions of plastic tape



Dimension of the Cavity is measured at the bottom side.

8.2 Specification of Taping

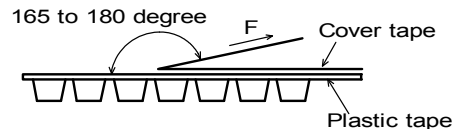
- (1) Packing quantity (standard quantity)
500 pcs / reel
- (2) Packing Method
Products shall be packed in the each embossed cavity of plastic tape and sealed by cover tape.
- (3) Sprocket hole
The sprocket holes are to the right as the tape is pulled toward the user.
- (4) Spliced point
Plastic tape and Cover tape has no spliced point.
- (5) Missing components number
Missing components number within 0.1 % of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

8.3 Pull Strength

Plastic tape	10N min.
Cover tape	5N min.

8.4 Peeling off force of cover tape

Speed of Peeling off	300mm / min
Peeling off force	0.2N to 0.7N (minimum value is typical)

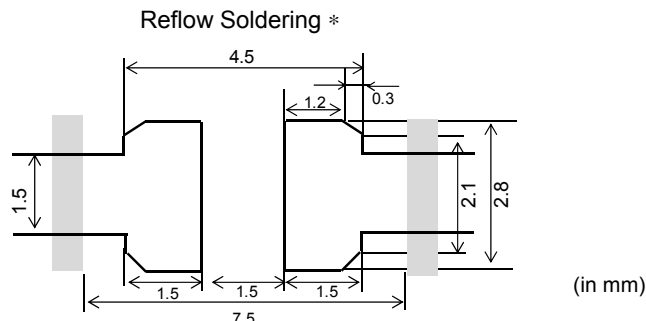


10. Notice

This product is designed for solder mounting.
Please consult us in advance for applying other mounting method such as conductive adhesive.

10.1 Land pattern designing

Recommended land patterns for reflow soldering are as follows:
It has been designed for Electric characteristics and solderability.
Please follow the recommended pattern. Otherwise, their performance which includes electrical performance or solderability may be affected, or result to "position shift" in soldering process.



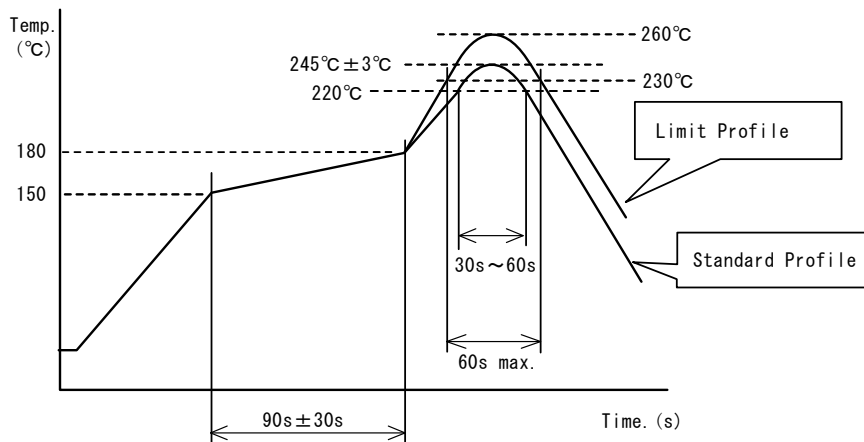
10.2 Flux, Solder

Flux	<ul style="list-style-type: none"> • Use rosin-based flux. • Don't use highly acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value). • Don't use water-soluble flux.
Solder	<ul style="list-style-type: none"> • Use Sn-3.0Ag-0.5Cu solder • Standard thickness of solder paste : 200µm to 300µm

Other flux (except above) Please contact us for details, then use.

10.3 Reflow soldering conditions

- Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150°C max. Cooling into solvent after soldering also should be in such a way that the temperature difference is limited to 100°C max.
Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of products quality.
- Standard soldering profile and the limit soldering profile is as follows.
The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.
- Reflow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150~180°C、90s±30s	
Heating	above 220°C、30s~60s	above 230°C、60s max.
Peak temperature	245±3°C	260°C,10s
Cycle of reflow	2 times	2time

10.4 Reworking with soldering iron.

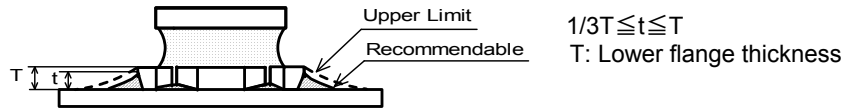
The following conditions must be strictly followed when using a soldering iron.

Pre-heating	150°C, 1 min
Tip temperature	350°C max.
Soldering iron output	80W max.
Tip diameter	φ 3mm max.
Soldering time	3(+1,-0)s
Times	2 times

Note : Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the products due to the thermal shock.

10.5 Solder Volume

- Solder shall be used not to be exceeded the upper limits as shown below.
- Accordingly increasing the solder volume, the mechanical stress to Chip is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

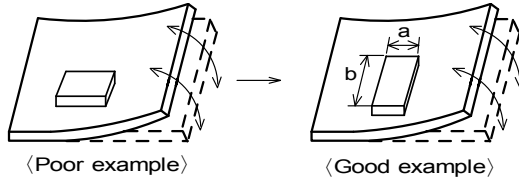


10.6 Product's location

The following shall be considered when designing and laying out P.C.B.'s.

- (1) P.C.B. shall be designed so that products are not subject to the mechanical stress due to warping the board.

[Products direction]

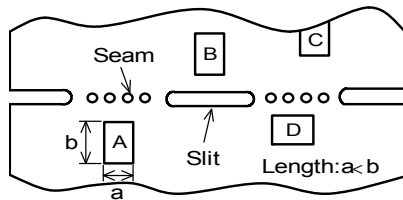


Products shall be located in the sideways direction (Length:a<b) to the mechanical stress.

- (2) Components location on P.C.B. separation.

It is effective to implement the following measures, to reduce stress in separating the board. It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

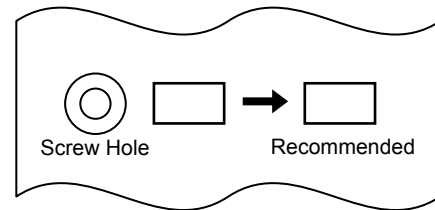
Contents of Measures	Stress Level
(1) Turn the mounting direction of the component parallel to the board separation surface.	A > D *1
(2) Add slits in the board separation part.	A > B
(3) Keep the mounting position of the component away from the board separation surface.	A > C



*1 A > D is valid when stress is added vertically to the perforation as with Hand Separation. If a Cutting Disc is used, stress will be diagonal to the PCB, therefore A > D is invalid.

- (3) Mounting Components Near Screw Holes

When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw. Mount the component in a position as far away from the screw holes as possible.



10.7 Cleaning Conditions

Products shall be cleaned on the following conditions.

- (1) Cleaning temperature shall be limited to 60°C max.(40°C max for alcohol type cleaner.)
- (2) Ultrasonic cleaning shall comply with the following conditions with avoiding the resonance phenomenon at the mounted products and P.C.B.
Power : 20 W / l max. Frequency : 28kHz to 40kHz Time : 5 min max.
- (3) Cleaner
 1. Alternative cleaner
 - Isopropyl alcohol (IPA)
 2. Aqueous agent
 - PINE ALPHA ST-100S
- (4) There shall be no residual flux and residual cleaner after cleaning.
In the case of using aqueous agent, products shall be dried completely after rinse with de-ionized water in order to remove the cleaner.
- (5) Other cleaning
Please contact us.

10.8 Resin coating

The inductance value may change due to high cure-stress of resin to be used for coating/molding products. An open circuit issue may occur by mechanical stress caused by the resin, amount/cured shape of resin, or operating condition etc. Some resin contains some impurities or chloride possible to generate chlorine by hydrolysis under some operating condition may cause corrosion of wire of coil, leading to open circuit. So, please pay your careful attention when you select resin in case of coating/molding the products with the resin. Prior to use the coating resin, please make sure no reliability issue is observed by evaluating products mounted on your board.

10.9 Caution for use

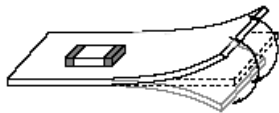
- Sharp material such as a pair of tweezers or other material such as bristles of cleaning brush, shall not be touched to the winding portion to prevent the breaking of wire.
- Mechanical shock should not be applied to the products mounted on the board to prevent the breaking of the core

10.10 Handling of a substrate

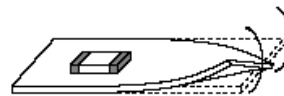
After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a coNZector from the substrate or tightening screw to the substrate.

Excessive mechanical stress may cause cracking in the product.

Bending



Twisting



10.11 Storage and Handling Requirements

- (1) Storage period
 - Use the products within 12 months after delivered.
 - Solderability should be checked if this period is exceeded.
- (2) Storage conditions
 - Products should be stored in the warehouse on the following conditions.
 - Temperature : -10 °C to 40 °C
 - Humidity : 15 % to 85 % relative humidity No rapid change on temperature and humidity
 - The electrode of the products is coated with solder. Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.
 - Products should not be stored on bulk packaging condition to prevent the chipping of the core and the breaking of winding wire caused by the collision between the products.
 - Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
 - Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.
- (3) Handling Condition
 - Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

11. ⚠ Note

- (1) Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2) You are requested not to use our product deviating from the reference specifications.
- (3) The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering